## SN5432, SN54LS32, SN54S32, SN7432, SN74LS32, SN74S32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

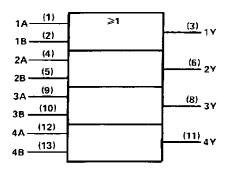
These devices contain four independent 2-input OR gates.

The SN5432, SN54LS32 and SN54S32 are characterized for operation over the full military range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN7432, SN74LS32 and SN74S32 are characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

#### **FUNCTION TABLE (each gate)**

INP	UTS	OUTPUT
Α	B	¥
Н	X	Н
Х	н	H
L	L	L

#### logic symbol†



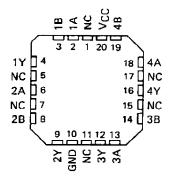
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D. J. N. or W packages.

SN5432, SN54LS32, SN54S32 . . . J OR W PACKAGE SN7432 . . . N PACKAGE SN74LS32, SN74S32 . . . D OR N PACKAGE (TOP VIEW)

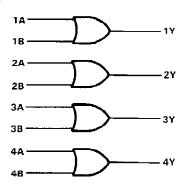
		<del></del>
1A 🗀	1	U14□ Vcc
1B 🗀	2	13 <b>□ 4B</b>
1Y 🗀	3	12 4A
2A 🗌	4	11 4Y
2B 🗀	5	10 3B
2Y [	6	9∏-3A
GND [	7	8 3Y
	_	

SN54LS32, SN54S32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

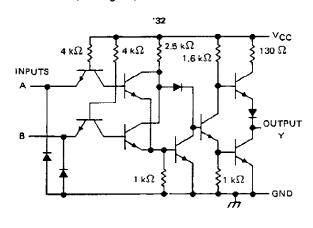
### logic diagram

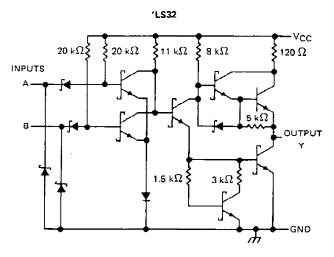


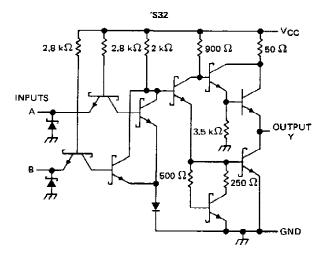
#### positive logic

 $Y = A + B \text{ or } Y = \overline{\overline{A} \cdot \overline{B}}$ 

#### schematics (each gate)







Resistor values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '32, 'S32	5.5 V
'L\$32	
Operating free-air temperature: SN54'	55°C to 125°C
SN74′	0°C to 70°C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

			SN5432			SN7432		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	OMIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
Уιн	Hgh-level input voltage	2			2			٧
VIL	Low-level imput voltage			0.8			8.0	V
Юн	High-level output current			- 0.8			8.0 ~	mA
loL	Low-level output current			16			16	mΑ
TA	Operating free-air temperature	- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS *		L	SN5432			UNIT		
PARAMETER		TEST CONDITIONS !			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	VCC = MIN.	lj = - 12 mA				- 1.5			<b>— 1</b> ,5	V
V <sub>QH</sub>	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	l <sub>OH</sub> = − 0,8 mA	2.4	3.4		2.4	3.4		V
VOL	V <sub>CC</sub> = MIN,	V <sub>1</sub> L ≈ 0.8 V,	IOL = 16 mA	7	0,2	0.4		0.2	0.4	V
l <sub>l</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V				1			1	mΑ
Чн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V				40		-	40	μА
lic.	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 1.6			- 1.6	mΑ
los§	VCC = MAX	·		- 20		<b>– 55</b>	- 18		- 55	mΑ
ГССН	V <sub>CC</sub> = MAX,	See Note 2			15	22		15	22	mA
<sup> </sup> CCL	V <sub>CC</sub> = MAX,	V1 = 0 V			23	38		23	38	mΑ

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

## switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN	TYP	MAX	UNIT	
tPLH !	A or B	>	B 400 O	C - 15 - 5		10	15	ns
†PHL	A 01 B	<u> </u>	$R_L = 400 \Omega$ ,	C <sub>L</sub> = 15 pF		14	22	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{\rm CC}$  = 5 V,  $T_{\rm A}$  = 25°C. § Not more than one output should be shorted at a time.

### SN54LS32, SN74LS32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

#### recommended operating conditions

		SN54LS32		SN74LS	532	TINU
	MIN	NOM MA	MIN	NOM	MAX 5.25 0.8 - 0.4 8	
V <sub>CC</sub> Supply voltage	4.5	5 5.	4.75	5	5.25	V
VIH Hgh-level input voltage	2		2			V
VIL Low-level input voltage		0.	7		8.0	V
IOH High-level output current		<b>– 0</b> .	4		- D.4	mA
IOL Low-level output current			4		8	mA
TA Opertating free-air temperature	- 55	12	5 0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST SOLIDITIONS 1			SN54LS	32					
PARAMETER		TEST CONDIT	IONST	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	UNIT
VIK	V <sub>CC</sub> - MIN,	I <sub>1</sub> = 18 mA				- 1.5			- 1.5	V
Voн	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OH</sub> = - 0.4 mA	2,5	3.4		2.7	3.4		V
	VCC - MIN,	VIL = MAX,	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	V <sub>CC</sub> = MIN,	VIL = MAX,	IOL = 8 mA	1				0.35	0.5	\
l <sub>1</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V		1		0.1			0.1	mA
IH	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V			<u>-</u>	20			20	μΑ
IIL	V <sub>CC</sub> = MAX,	V   = 0.4 V		ļ		0.4			- 0.4	mΑ
<sup>I</sup> OS§	VCC = MAX		·	- 20		- 100	<b>– 20</b>		<b>- 100</b>	mΑ
іссн	V <sub>CC</sub> = MAX,	See Note 2			3,1	6.2		3.1	6.2	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0 V		i	4.9	9.8		4.9	9.8	mΑ

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: One input at 4.5 V, all others at GND.

### switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDIT	MIN	ТҮР	МАХ	UNIT	
tPLH .	A or B	V	D - 11.0	C = 15 ==		14	22	пѕ
†PHL	AOLD	•	$R_{\perp} = 2 k\Omega$ ,	C <sub>L</sub> = 15 p <sub>F</sub>		14	22	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . § Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

## recommended operating conditions

	<del></del>		SN54S3	2		SN74S3	2	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			8.0			0.8	V
Іон	High-level output current			1			<b>– 1</b>	mΑ
loL	Low-level output current			20			20	mΑ
TA	Operating free-air temperature	- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	TIONS T	L.	SN54S3	2		SN74S3	2	
PARAMETER		TEST COMDITIONS :				MAX	MIN	TYP #	MAX	UNIT
V <sub>IK</sub>	VCC = MIN,	lj = _ 18 mA				- 1.2		-	- 1.2	V
Voн	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	IOH = - 1 mA	2.5	3.4		2.7	3.4		V
Vol	VCC = MIN,	V <sub>IL</sub> = 0.8 V,	I <sub>OL</sub> = 20 mA			0.5	T		0.5	V
li l	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 5.5 V				1		-	1	mA
Чн	VCC = MAX,	V <sub>1</sub> = 2.7 V				50			50	μА
lIL.	VCC = MAX,	V <sub>1</sub> = 0.5 V			·	-2			- 2	mA
los§	V <sub>CC</sub> = MAX	-		- 40		<b>- 100</b>	- 40		<b>–</b> 100	mA
<sup>1</sup> ссн	V <sub>CC</sub> = MAX,	See Note 2			18	32		18	32	mA
ICCL	VCC = MAX,	V <sub>1</sub> = 0 V			38	68		38	68	mA

- † For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
- ‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. § Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.
- NOTE 2: One input at 4.5 V, all others at GND.

## switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TY	P MAX	UNIT
t <sub>PLH</sub>	A or B	V	D - 200 C	C <sub>1</sub> = 15 pF		4 7	ns
tPHL .	AOFB	Y	R <sub>L</sub> = 280 Ω,	С[ - 15 рг		4 7	ns
<sup>t</sup> PLH	A or 8		$R_1 = 280 \Omega$ ,	C <sub>I</sub> = 50 pF		ĵ	п\$
tpHL	70.8	<u> </u>	71 <u>L</u> 200 82,			5	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9557401QCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QC A SNJ5432J	Samples
5962-9557401QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QD A SNJ5432W	Samples
5962-9557401QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QD A SNJ5432W	Samples
JM38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30501B2A	Samples
JM38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30501B2A	Samples
JM38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BCA	Samples
JM38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BCA	Samples
JM38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BDA	Samples
JM38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BDA	Samples
JM38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SCA	Samples
JM38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SCA	Samples
JM38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SDA	Samples
JM38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SDA	Samples
M38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30501B2A	Samples
M38510/30501B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30501B2A	Samples
M38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BCA	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)				-	(2)		(3)		(4/5)	
M38510/30501BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BCA	Samples
M38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501BDA	Samples
M38510/30501BDA	ACTIVE	CFP	W	14	1	TBD	A42 N / A for Pkg Type -55 to 125		-55 to 125	JM38510/ 30501BDA	Samples
M38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SCA	Samples
M38510/30501SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SCA	Samples
M38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SDA	Samples
M38510/30501SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30501SDA	Samples
SN5432J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5432J	Samples
SN5432J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN5432J	Samples
SN54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS32J	Samples
SN54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS32J	Samples
SN54S32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S32J	Samples
SN54S32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S32J	Samples
SN7432N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7432N	Samples
SN7432N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7432N	Samples
SN7432N3	OBSOLET	E PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7432N3	OBSOLET	E PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7432NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7432N	Samples
SN7432NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7432N	Samples
SN74LS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L\$32	Samples



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS CU NIPDAU Level-1-260C-UNLIM 0 to 70 & no Sb/Br)		0 to 70	LS32	Samples	
SN74LS32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Samples
SN74LS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS32	Sample
SN74LS32J	OBSOLETI	E CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS32J	OBSOLETI	E CDIP	J	14		TBD	Call TI	Call TI	0 to 70		



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74LS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS32N	Sample
SN74LS32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS32N	Sample
SN74LS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS32N	Sample
SN74LS32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS32N	Sample
SN74LS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS32	Sample
SN74LS32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS32	Sample
SN74LS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS32	Sample
SN74LS32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS32	Sample
SN74S32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample



Orderable Device	Status	Package Type	Package Drawing	Pins P	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74S32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S32	Sample
SN74S32DRG4	ACTIVE	SOIC	& no Sb/Br)		0 to 70	S32	Sample				
SN74S32N	ACTIVE	PDIP	N	N 14 25 Pb-Free CU NIPDAU N / A for Pkg Type 0 to 70 (RoHS)		0 to 70	SN74S32N	Sample			
SN74S32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S32N	Sample
SN74S32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S32N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S32N	Sample
SN74S32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S32N	Sample
SNJ5432J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QC A SNJ5432J	Sample
SNJ5432J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QC A SNJ5432J	Sample
SNJ5432W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QD A SNJ5432W	Sample
SNJ5432W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9557401QD A SNJ5432W	Sample
SNJ54LS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 32FK	Sample
SNJ54LS32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 32FK	Sample
SNJ54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS32J	Sample
SNJ54LS32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS32J	Sample





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Orderable Device	Status	Package Type	Package Drawing			Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)				Qty	(2)		(3)		(4/5)	
SNJ54LS32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS32W	Samples
SNJ54LS32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS32W	Samples
SNJ54S32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 32FK	Samples
SNJ54S32FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S 32FK	Samples
SNJ54S32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S32J	Samples
SNJ54S32J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S32J	Samples
SNJ54S32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S32W	Samples
SNJ54S32W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S32W	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



### PACKAGE OPTION ADDENDUM

25-Sep-2013

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN5432, SN54LS32, SN54LS32-SP, SN54S32, SN74S3, SN74LS32, SN74S32:

Catalog: SN7432, SN74LS32, SN54LS32, SN74S32

Military: SN5432, SN54LS32, SN54S32

Space: SN54LS32-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

## PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS32DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74S32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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#### \*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS32DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LS32DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74S32DR	SOIC	D	14	2500	367.0	367.0	38.0

## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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